



## Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
APB3227SEKCGKC	Super Bright Orange (AlGaInP)	Water Clear	120	250	100°
			*80	*180	
	Green (AlGaInP)		20	55	
			*20	*55	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity/ luminous Flux: +/-15%.

\* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Orange Green	610 574		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Orange Green	601 570		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Orange Green	29 20		nm	IF=20mA
C	Capacitance	Super Bright Orange Green	15 15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Orange Green	2.1 2.1	2.5 2.5	V	IF=20mA
IR	Reverse Current	Super Bright Orange Green		10 10	uA	VR = 5V

Notes:

1.Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

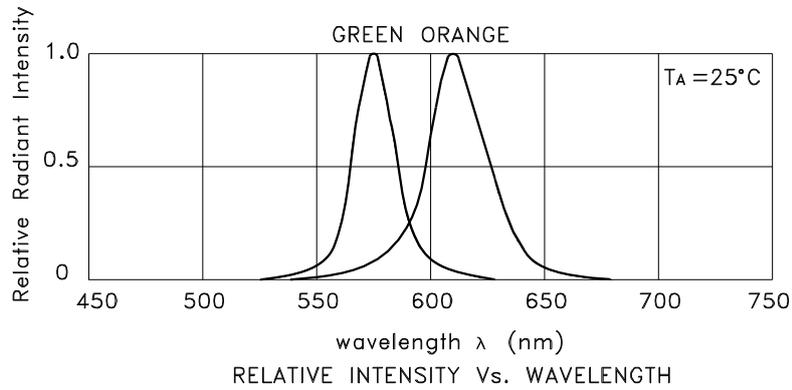
3.Wavelength value is traceable to the CIE127-2007 compliant national standards.

## Absolute Maximum Ratings at TA=25°C

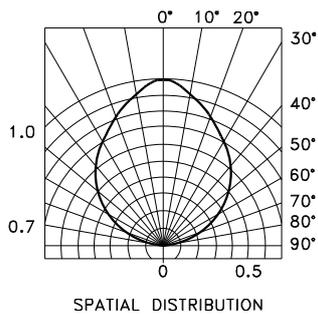
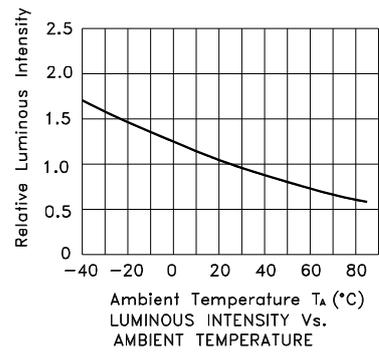
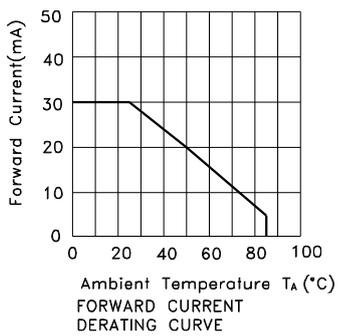
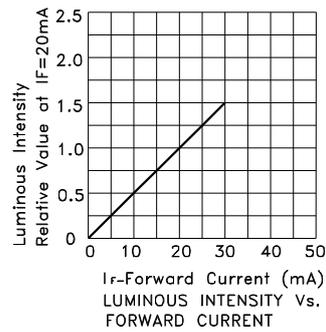
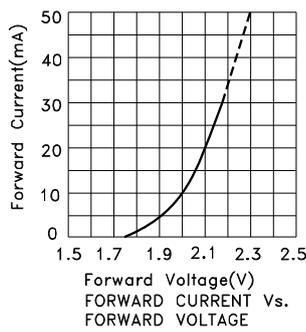
Parameter	Super Bright Orange	Green	Units
Power dissipation	75	75	mW
DC Forward Current	30	30	mA
Peak Forward Current [1]	195	150	mA
Reverse Voltage	5		V
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Note:

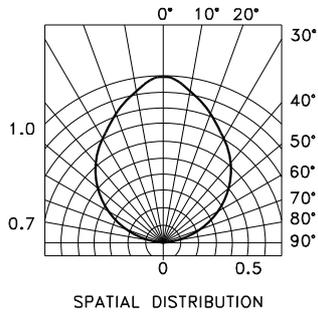
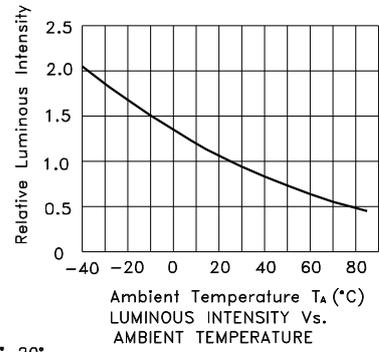
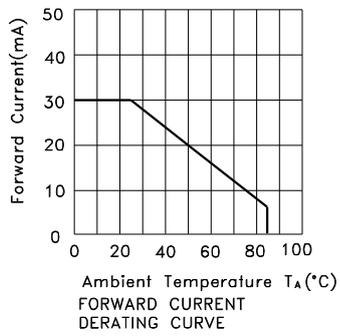
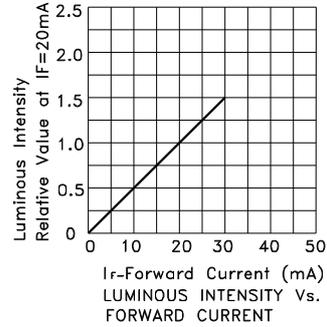
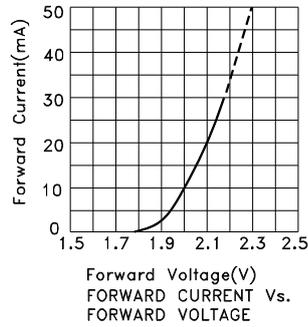
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



## APB3227SEKCGKC Super Bright Orange



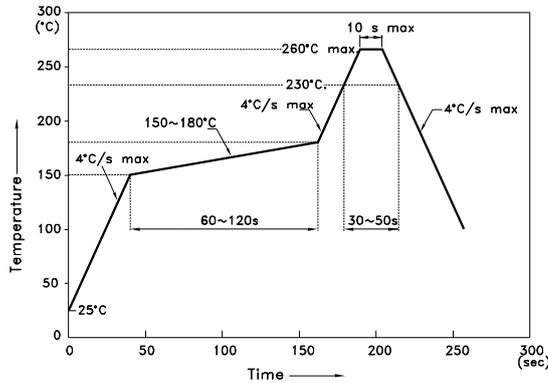
## Green



## APB3227SEKCGKC

Reflow soldering is recommended and the soldering profile is shown below.  
Other soldering methods are not recommended as they might cause damage to the product.

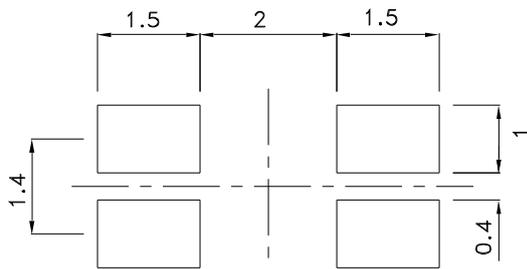
Reflow Soldering Profile For Lead-free SMT Process.



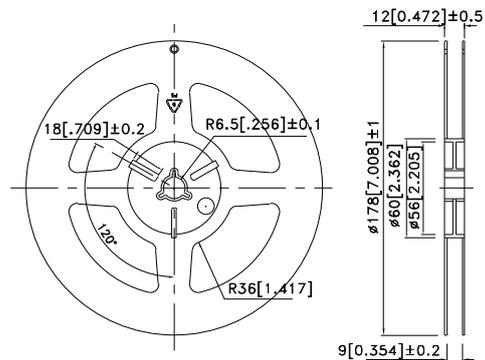
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

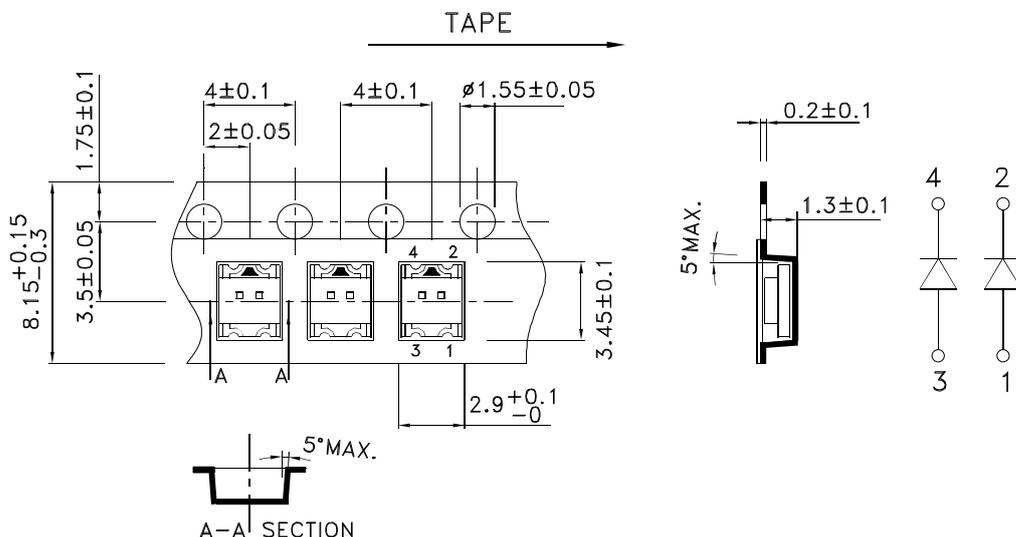
### Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



### Reel Dimension



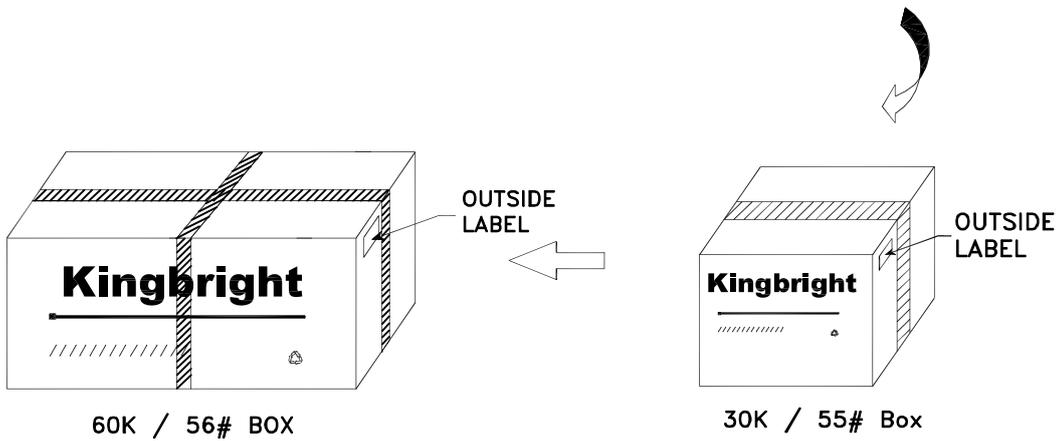
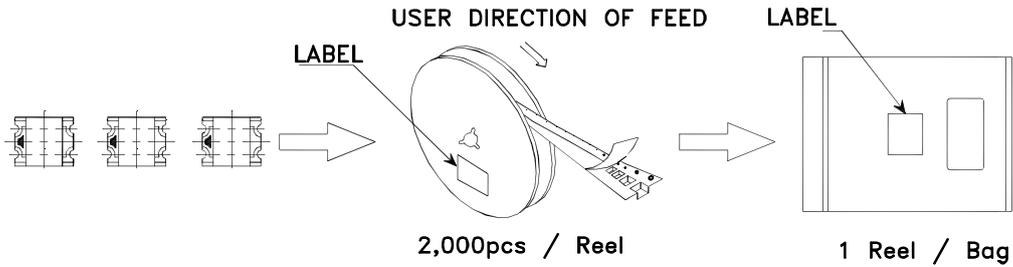
### Tape Dimensions (Units : mm)



# Kingbright

PACKING & LABEL SPECIFICATIONS

APB3227SEKCGKC



<h1>Kingbright</h1>	
P/NO: APB3227XXX	
QTY: 2,000 pcs	Q.C. <span style="border: 1px solid black; border-radius: 50%; padding: 2px;">Q C XX-XX-XXXX PASSED</span>
S/N: XXXX	
CODE: XXX	
LOT NO:	
	
RoHS Compliant	

All design applications should refer to Kingbright application notes available at <http://www.KingbrightUSA.com/ApplicationNotes>